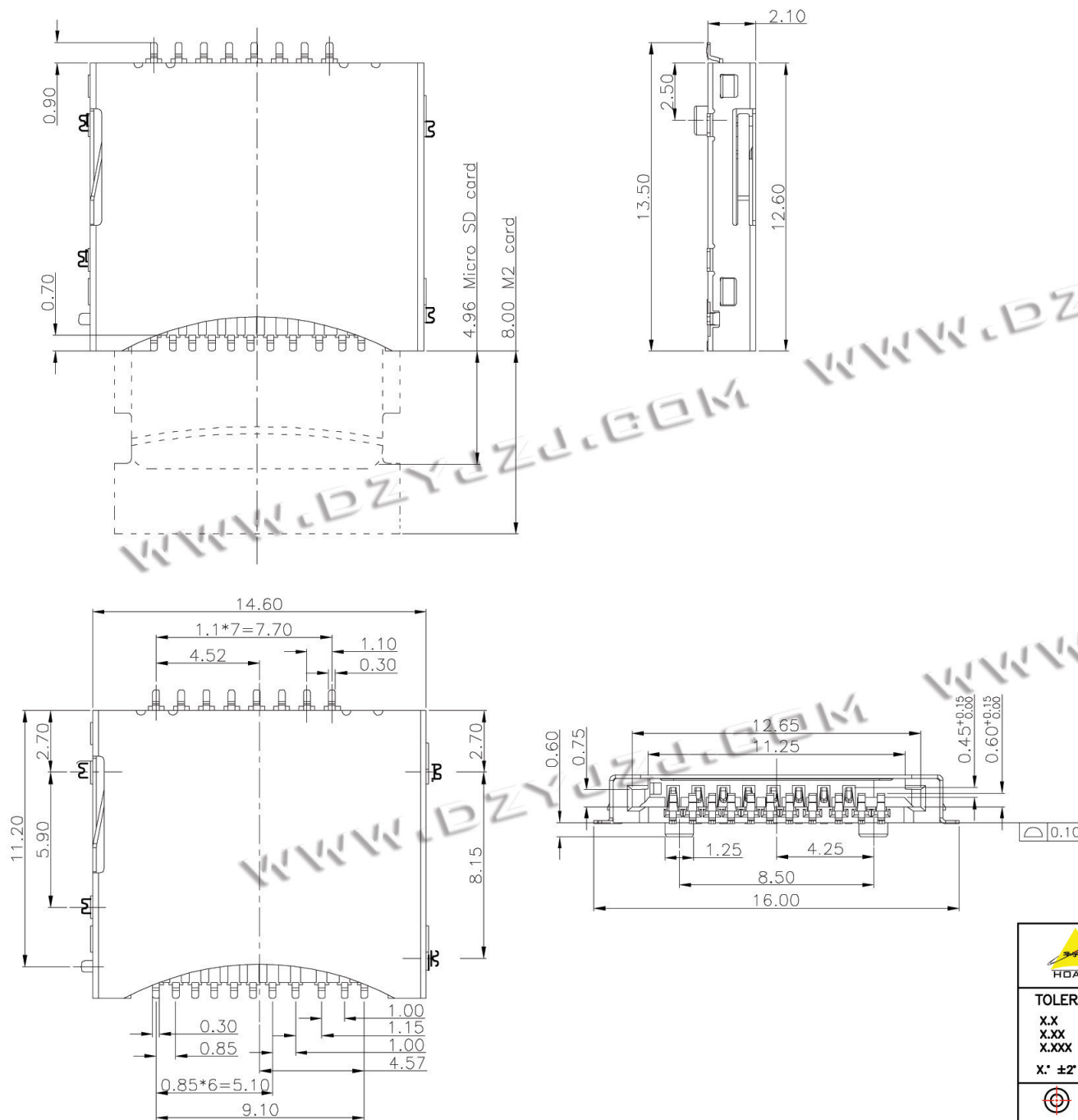




SPECIFICATION

1.MATERIAL

Insulator: High Temperature Thermoplastic,
UL94V-0

Contact: Copper Alloy

Shell: Copper Alloy

2.PLATING

Contact Area: Gold PLATED Over Ni.

Solder Tail: Sn PLATED Over Ni.

Shell Solder Area: Gold PLATED Over Ni.

3.ELECTRICAL

Operating Temperature: -25°C TO +90°C

Current Rating :0.5mA max.

Contact Resistance:100mΩ max.

Insulation Resistance:1000MΩ min./500VDC

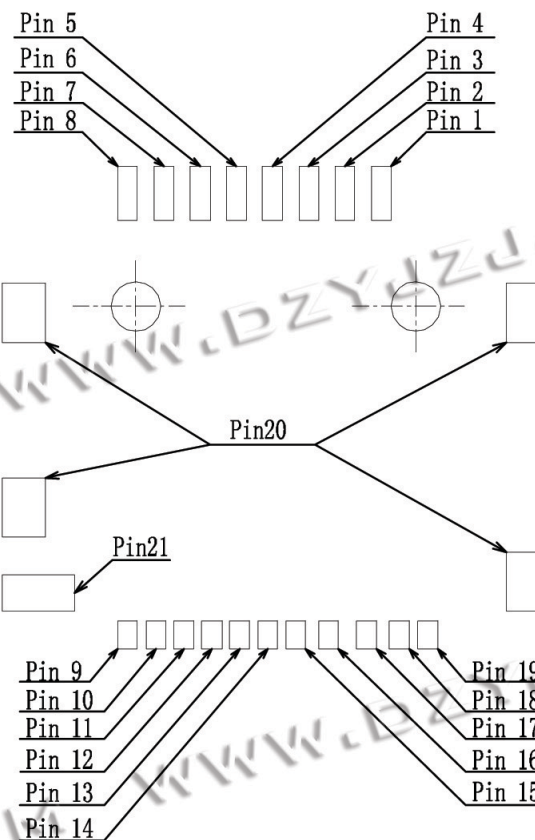
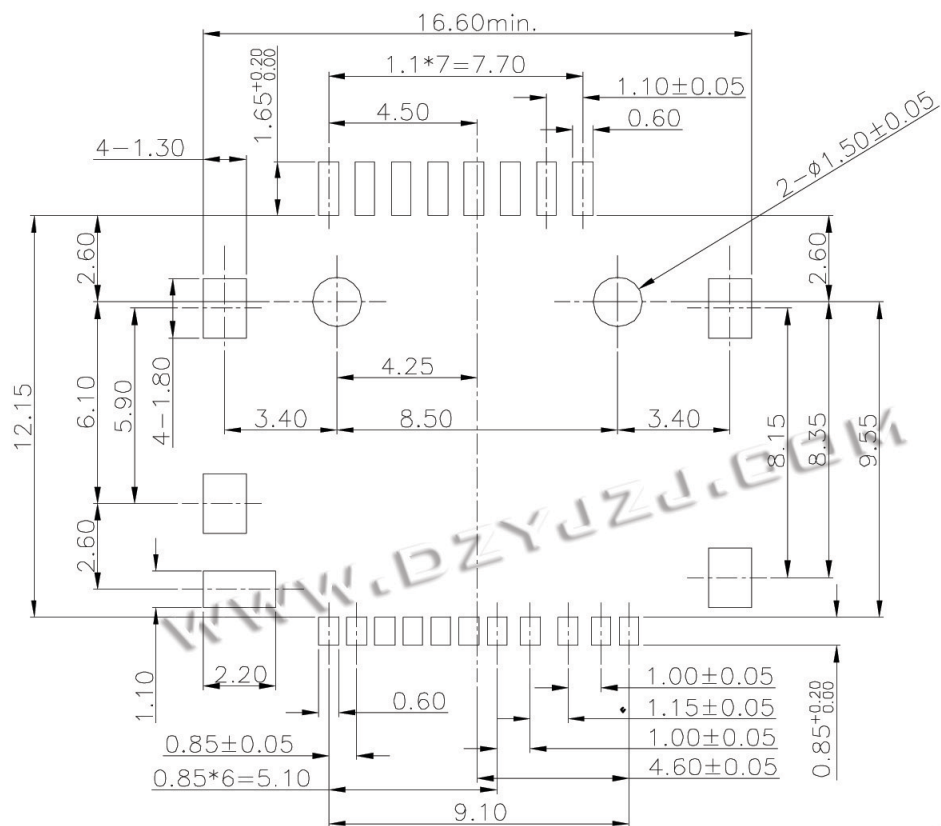
4.MECHANICAL

Mating Cycles:10,000 Insertions



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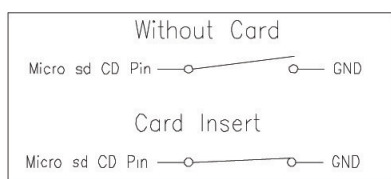
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2° X.X' ±0.5°	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: Micro SD+M2
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC75-2IN121-210
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2307241657
			SHEET NO. 1 OF 1



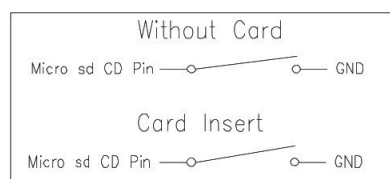
pin NO.	Description
Pin 01	Micro-SD_DAT2
Pin 02	Micro-SD_CD/DAT3
Pin 03	Micro-SD_CMD
Pin 04	Micro-SD_VDD
Pin 05	Micro-SD_CLK
Pin 06	Micro-SD_VSS
Pin 07	Micro-SD_DAT0
Pin 08	Micro-SD_DAT1
Pin 09	M2_BS
Pin 10	M2_DIO1
Pin 11	M2_DIO0
Pin 12	M2_DIO2
Pin 13	M2_INS
Pin 14	M2_DIO3
Pin 15	M2_SCLK
Pin 16	M2_VCC
Pin 17	M2_CSS
Pin 18	M2_RESERVED
Pin 19	M2_RESERVED
Pin 20	GND
Pin 21	Micro SD C/D Pin

RECOMMENDED PCB LAYOUT
(GENERAL TOLERANCE ± 0.05)

Micro sd Card Insert



M2 Card Insert



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TOLERANCE:

X.X ± 0.30

X.XX ± 0.25

X.XXX ± 0.15

X' $\pm 2'$ X.X' $\pm 0.5'$

UNIT: mm [inch]

SCALE: 1:1 SIZE: A4

DRAWN BY:

陈一鸣

DATE:

2014-02-23

PART NAME:

Micro SD+M2

CHECKED BY:

马跃

DATE:

2014-02-23

PART NO.

HYC75-2IN121-210

MOLD NO.

DRAW NO:

HYC-2307241657

SHEET NO.

1 OF 1

APPROVED BY:

邱敏

DATE:

2014-02-23